

1. Part No. Expression

**W 3 F 6 7 0 - R D - 1 0**

(a)(b)(c) (d) (e)(f) (g)

(a) Series Code

(b) Dimension Code

(c) Material Code

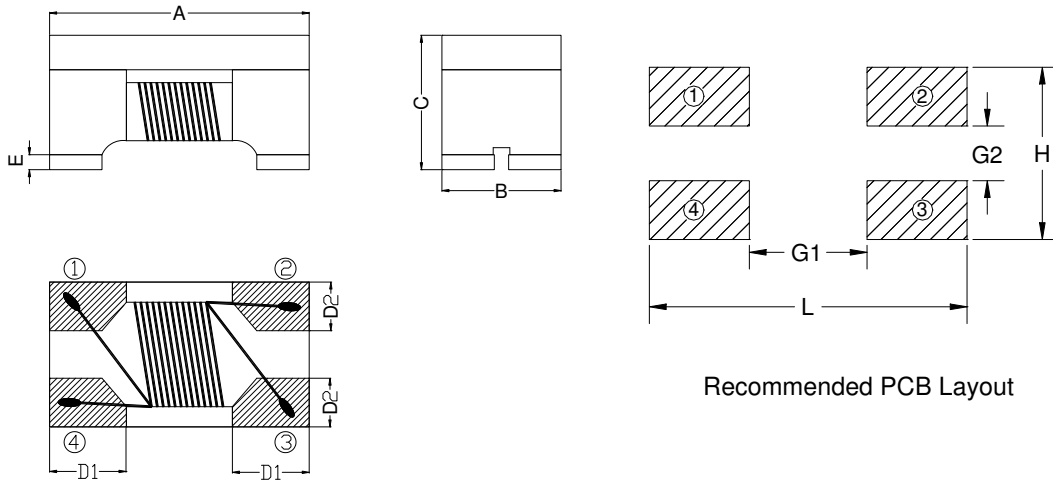
(d) Impedance Code

(e) Packaging Code

(f) Current Rating Code

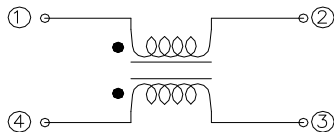
(g) Special Code

2. Configuration & Dimensions: (Unit:- mm)



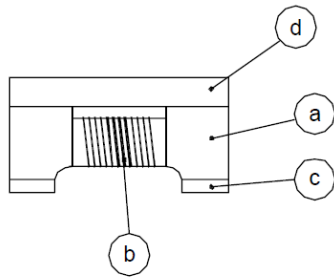
A	B	C	D1	D2	E	L	G1	G2	H
2.0±0.2	1.2±0.2	1.2±0.2	0.50±0.1	0.51±0.1	0.15±0.1	2.60 Ref	1.25 Ref	0.45 Ref	1.40 Ref

3. Schematic



NOTE: Specifications subject to change without notice. Please check our website for latest information.

4. Material List



- (a) Core
- (b) Wire
- (c) Terminal
- (d) Upper Plate

5. General Specifications

- (a) Operating Temp. : -40°C to +125°C (Including self - temperature rise).
- (b) Storage Temp. : -40°C to +125°C (On board).
- (c) Irms: Based on temperature rise  $\Delta T$  40°CMax at rated current.
- (d) Storage Condition (Component in its packaging)
  - i) Temperature: Less than 40°C
  - ii) Humidity: 60% RH

6. Electrical Characteristics

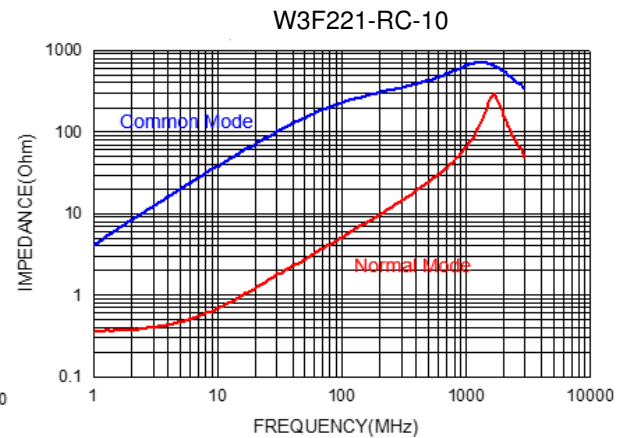
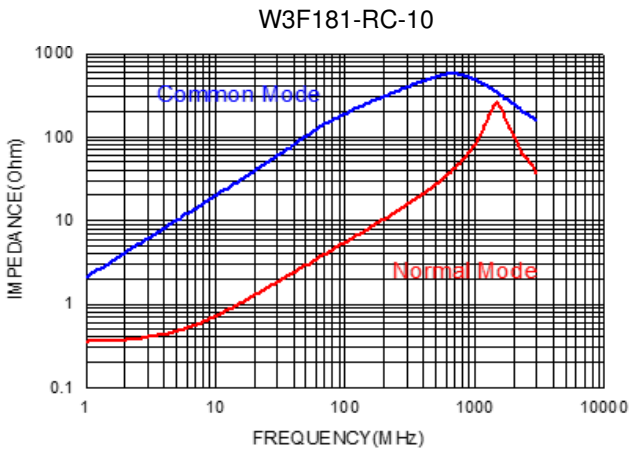
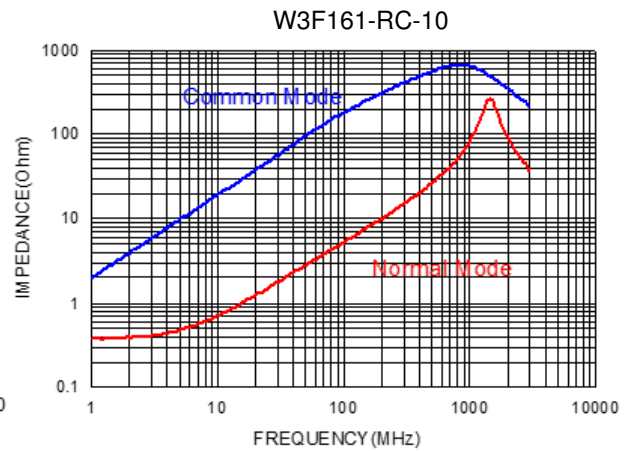
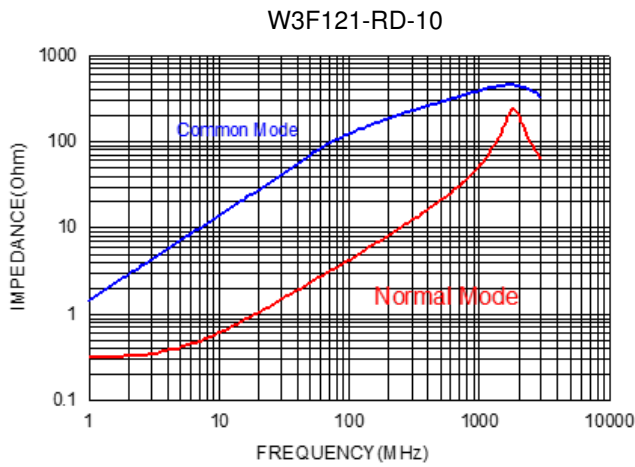
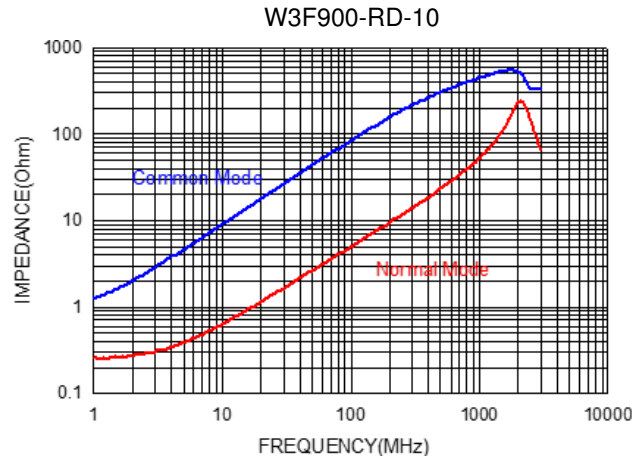
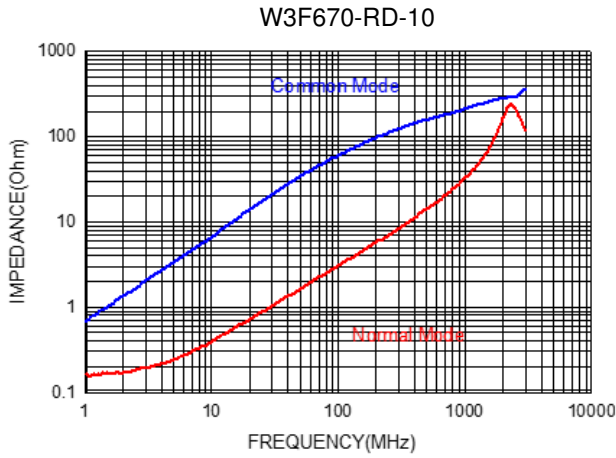
Part Number	Common Mode Impedance ( $\Omega$ )	Test Frequency (MHz)	DC Resistance ( $\Omega$ ) Max.	Rated Current (mA) Max.	Rated Volt. (Vdc) Max.	Withstand Volt. (Vdc) Max.	IR ( $\Omega$ ) Min.
W3F670-RD-10	67 $\pm$ 25%	100	0.25	400	50	125	10M
W3F900-RD-10	90 $\pm$ 25%	100	0.30	400	50	125	10M
W3F121-RD-10	120 $\pm$ 25%	100	0.30	400	50	125	10M
W3F161-RC-10	160 $\pm$ 25%	100	0.35	350	50	125	10M
W3F181-RC-10	180 $\pm$ 25%	100	0.35	350	50	125	10M
W3F221-RC-10	220 $\pm$ 25%	100	0.40	300	50	125	10M
W3F261-RC-10	260 $\pm$ 25%	100	0.40	300	50	125	10M
W3F361-RC-10	360 $\pm$ 25%	100	0.50	300	50	125	10M

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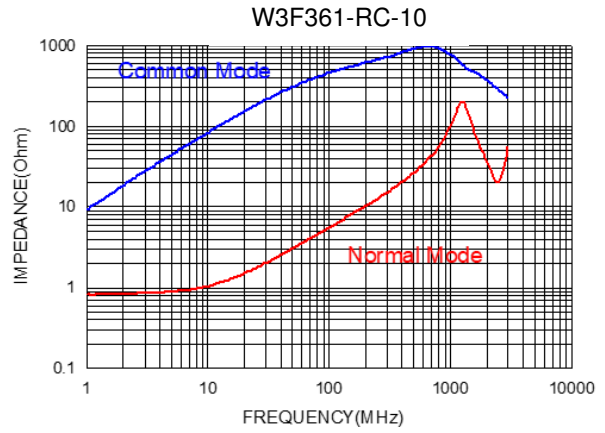
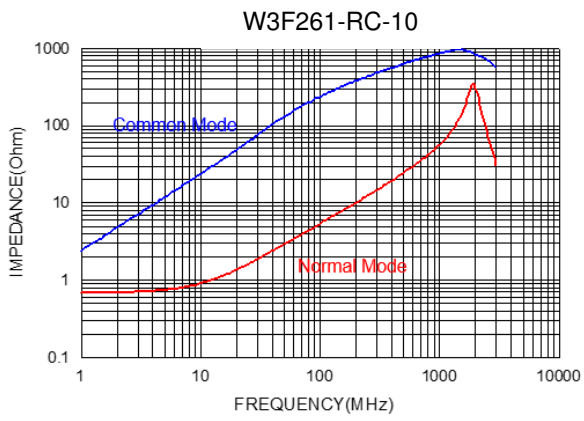
7. Characteristics Curves

7-1 Impedance vs Frequency

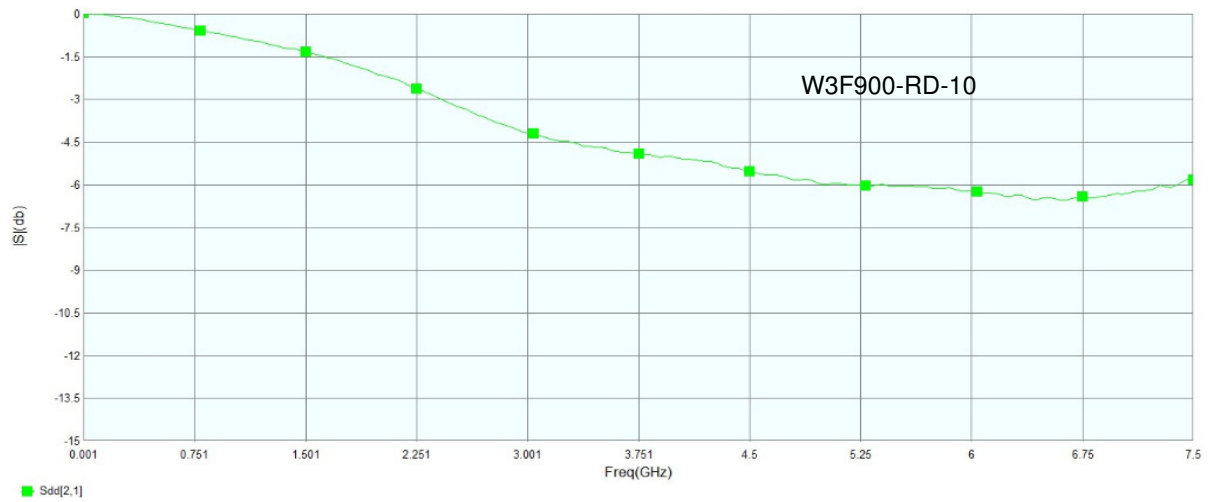
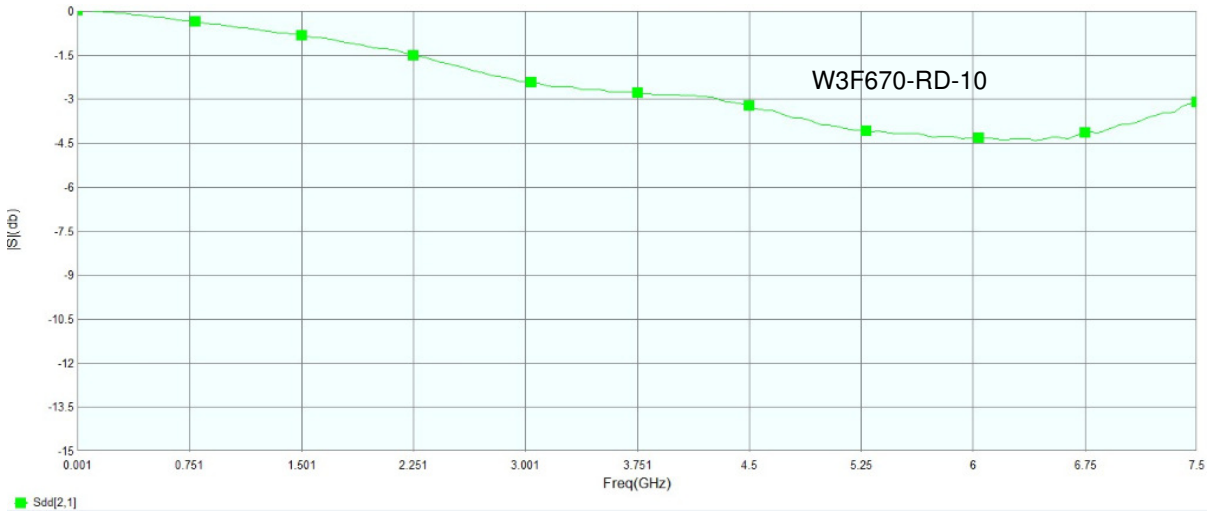


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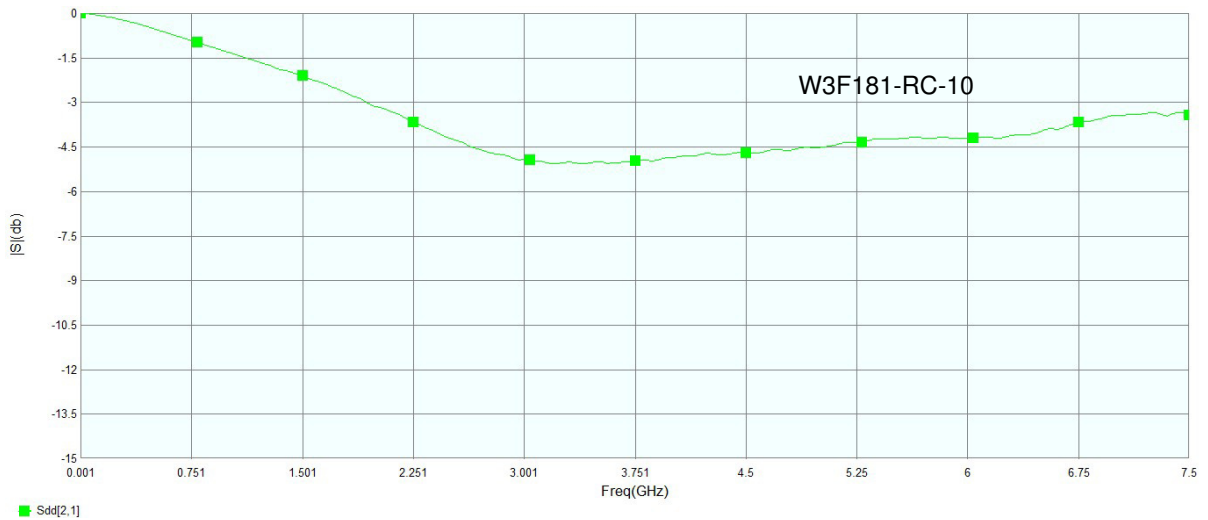
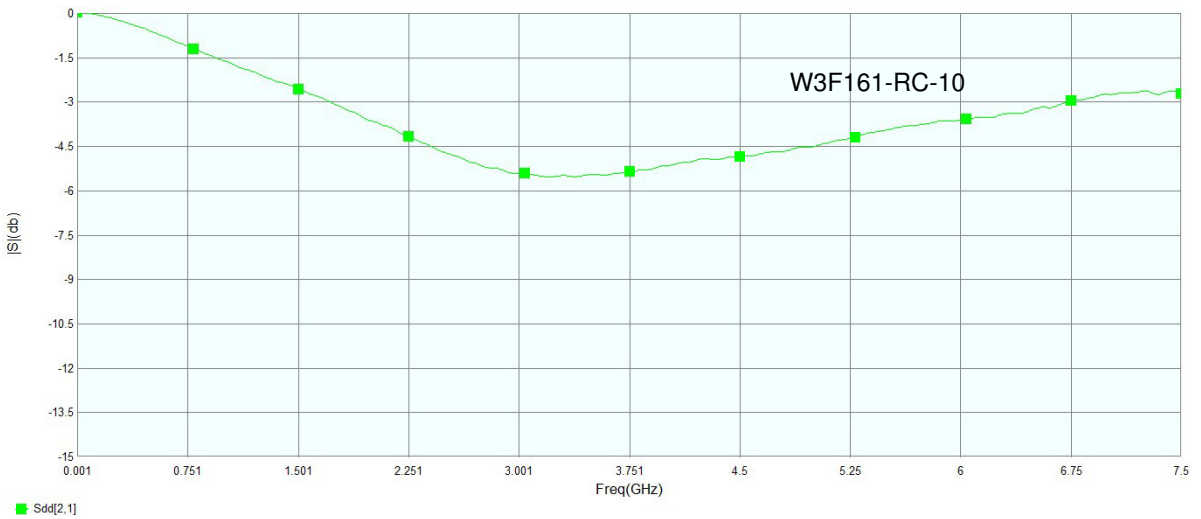
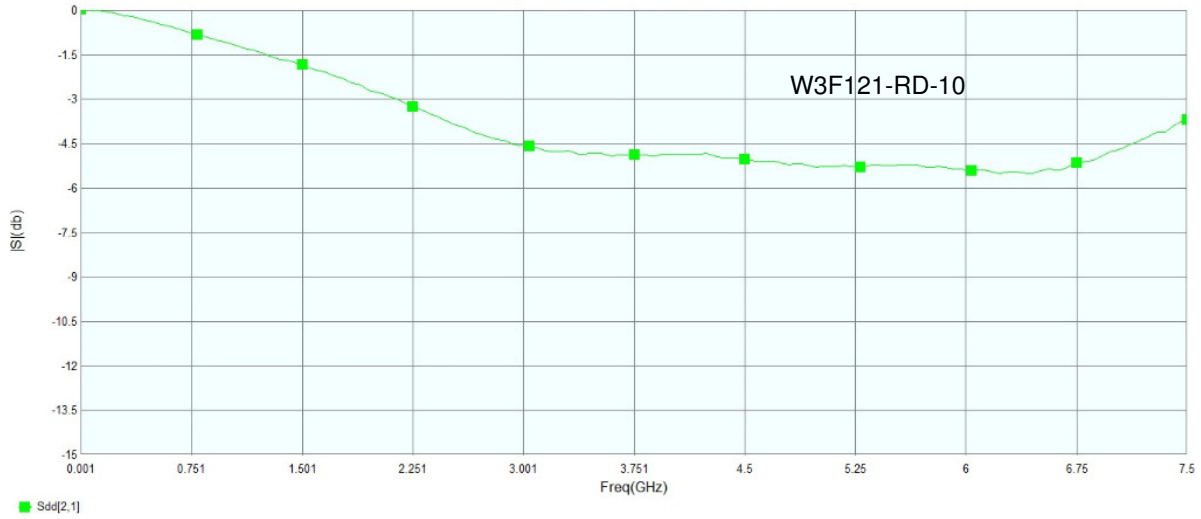


7-2 Insertion Loss Test



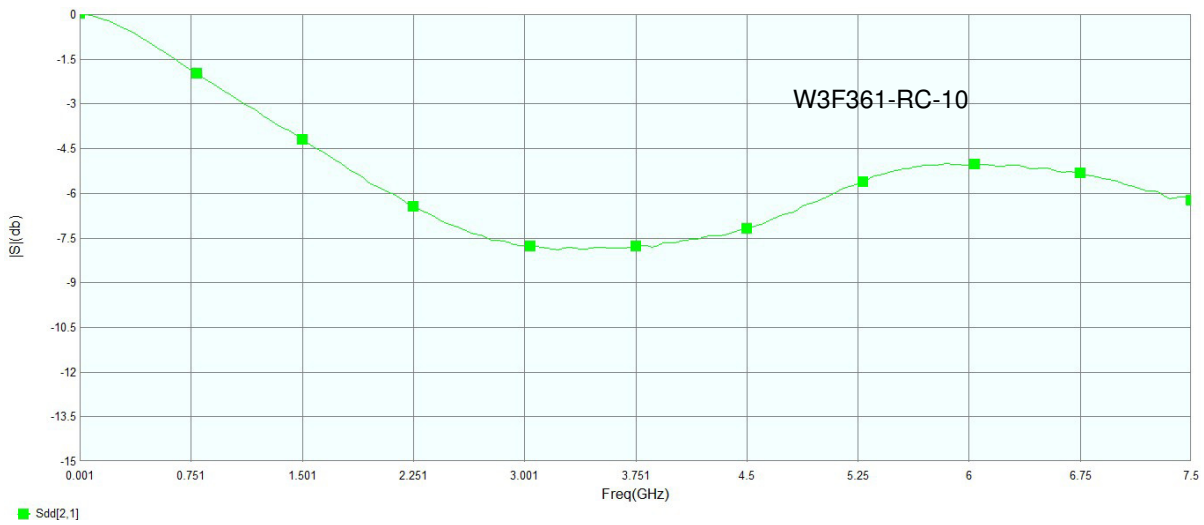
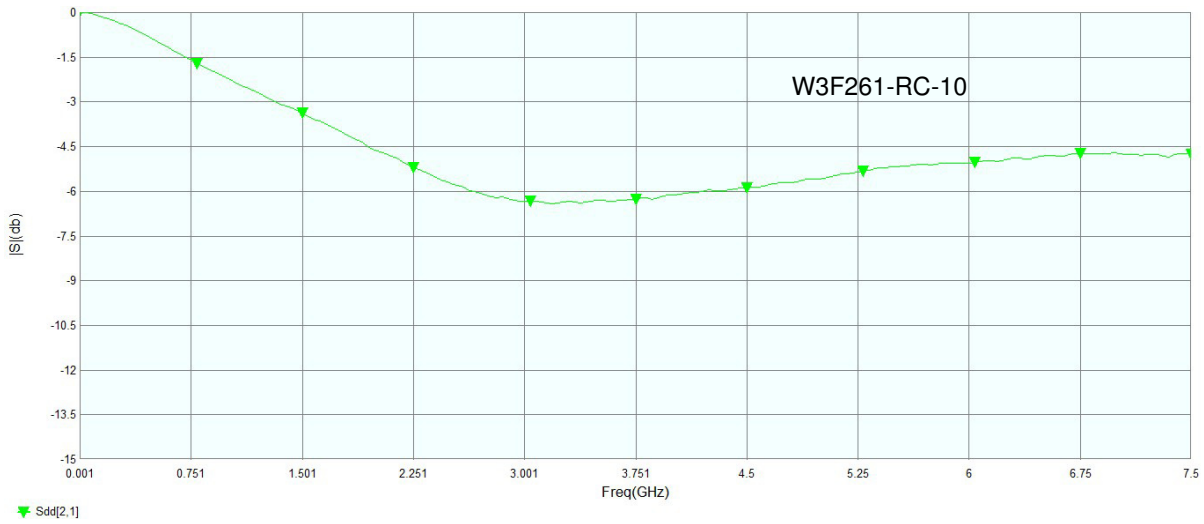
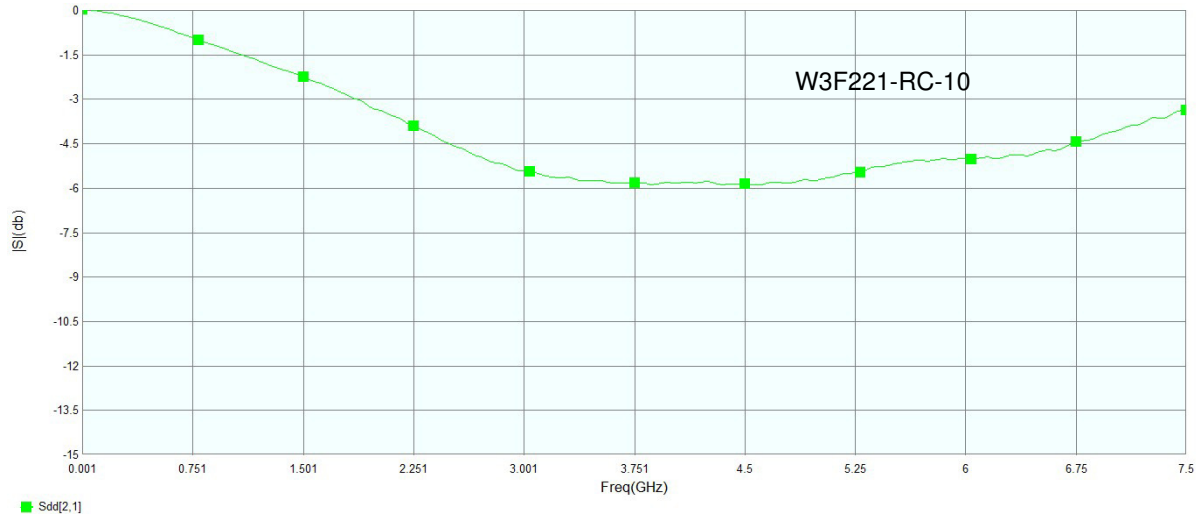
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## 8. Soldering and Mounting

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### 8-1 Solder Re-flow

Recommended temperature profiles for re-flow soldering in Figure 1.

### 8-2 Soldering Iron (Figure 2)

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note:

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 sec.

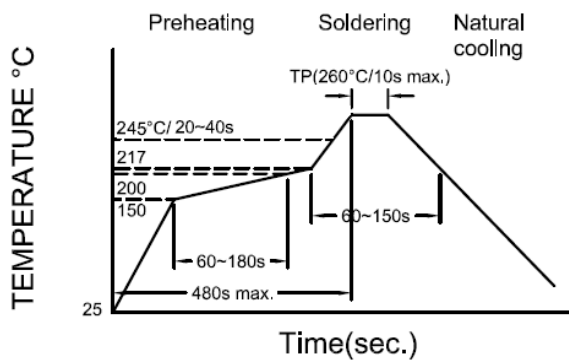


Figure 1. : Re-flow Soldering time  
3 times Max

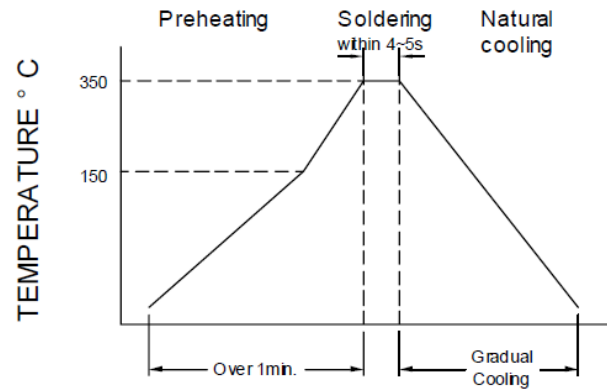
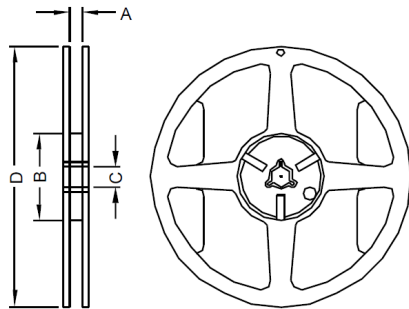


Figure 2. : Iron Soldering time  
1 times Max

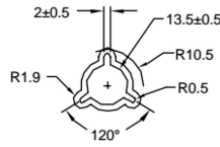
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9. Packaging Information

9-1 Reel Dimension

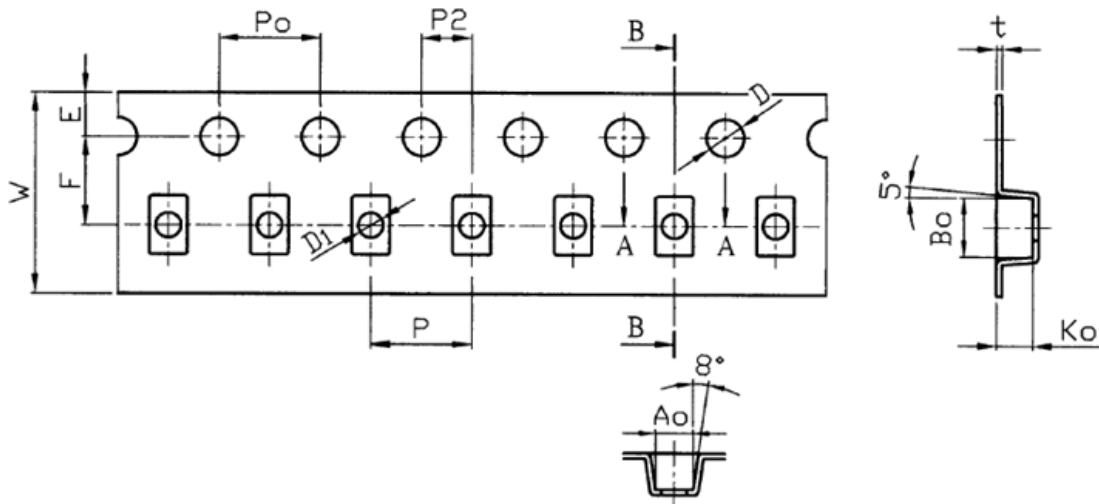


7" x 8mm



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60.0±2.0	13.5±0.5	178.0±2.0

9-2 Tape Dimension / 8mm



Size	W(mm)	P(mm)	E(mm)	F(mm)	P2(mm)	D(mm)
	8.00±0.10	4.00±0.10	1.75±0.10	3.50±0.05	2.00±0.05	1.50+0.10/-0.00
W3F	D1(mm)	P0(mm)	A0(mm)	B0(mm)	K0(mm)	t(mm)
	1.00±0.10	4.00±0.10	1.50±0.10	2.35±0.10	1.45±0.10	0.28±0.05

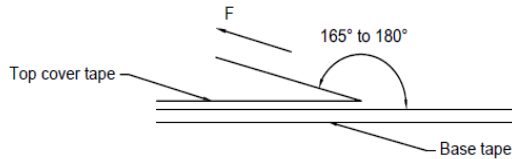
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### 9-3 Packaging Quantity

Chip Size	W3F
Chip/Reel	2,000
Inner Box	10,000
Middle Box	50,000
Carton	100,000

### 9-4 Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

### Application Notice:

#### 1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

#### 2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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